

Silicon NPN Power Transistors

BUS14

DESCRIPTION

- With TO-3 package
- High voltage ,high speed

APPLICATIONS

- Converters
- Inverters
- Switching regulators
- Motor controls

PINNING (See Fig.2)

PIN	DESCRIPTION
1	Base
2	Emitter
3	Collector

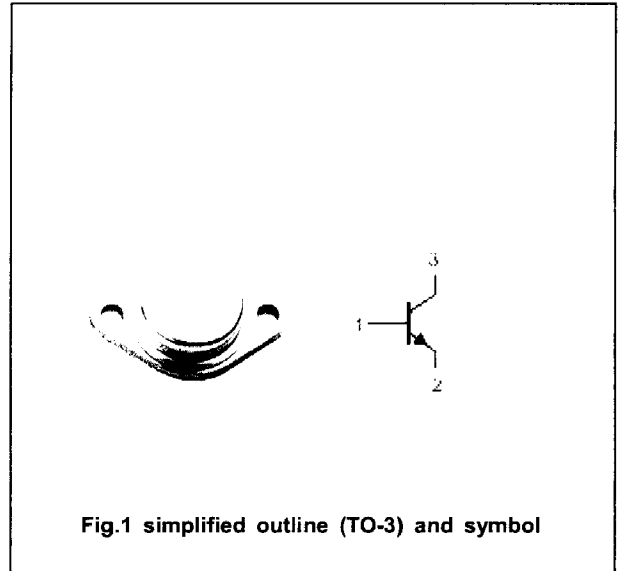


Fig.1 simplified outline (TO-3) and symbol

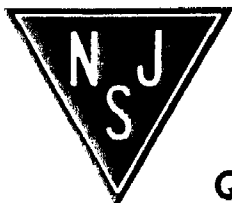
Absolute maximum ratings(Ta=25°C)

SYMBOL	PARAMETER	CONDITIONS	MAX	UNIT
V _{CB0}	Collector-base voltage	Open emitter	850	V
V _{CEO}	Collector-emitter voltage	Open base	400	V
V _{EBO}	Emitter-base voltage	Open collector	9	V
I _C	Collector current		30	A
I _{CM}	Collector current-Peak		50	A
I _B	Base current		6	A
I _{BM}	Base current-Peak		10	A
P _T	Total power dissipation	T _{mb} =25	250	W
T _j	Junction temperature		200	
T _{stg}	Storage temperature		-65~200	

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-mb}	Thermal resistance from junction to mounting base	0.7	/W

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CHARACTERISTICS

T_j=25 unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
V _{CE(SUS)}	Collector-emitter sustaining voltage	I _C =0.1A; I _B =0; L=25mH	400			V
V _{CE(sat)}	Collector-emitter saturation voltage	I _C =20A; I _B =4A			1.5	V
V _{BE(sat)}	Base-emitter saturation voltage	I _C =20A; I _B =4A			1.7	V
I _{CES}	Collector cut-off current	V _{CE} =RatedBV _{CEO} ; V _{BE} =0 T _C =125			1 5	mA
I _{EBO}	Emitter cut-off current	V _{EB} =9V; I _C =0			10	mA
h _{FE}	DC current gain	I _C =2A; V _{CE} =5V	15		50	

Switching times

t _{on}	Turn-on time	I _C =20A; I _{B1} =- I _{B2} =4A			1.0	μs
t _s	Storage time				4.0	μs
t _f	Fall time				0.8	μs

PACKAGE OUTLINE

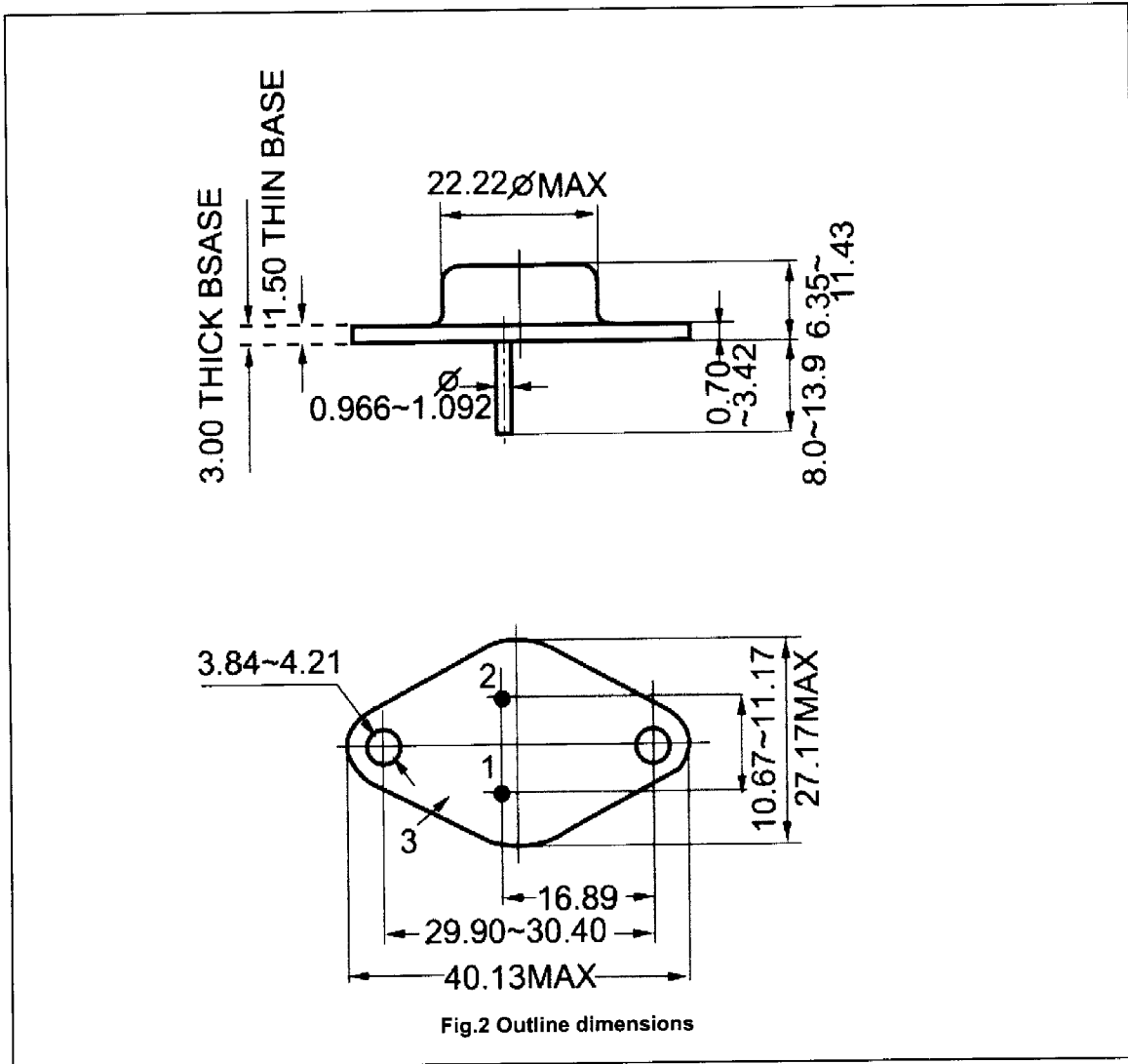


Fig.2 Outline dimensions